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## FACSIMILE COVER SHEET

To: Tuan T. Dinh  
Art Unit 2827

From: Daniel J. Bedell

Firm: US PATENT AND  
TRADEMARK OFFICE

Date: June 12, 2003

Fax: 1-703-872-9319

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Your ref: 09/970,749

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REPLY UNDER 37 CFR 1.116  
EXPEDITED PROCEDURE  
EXAMINING GROUP 2827

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Charles A. MILLER

Art Unit: 2827

Application No: 09/970,749

Examiner:  
Tuan T. Dinh

Filed: October 3, 2001

For: MULTIPLE DIE INTERCONNECT SYSTEM

REPLY TO THE OFFICE ACTION MAILED 04/09/2003  
AMENDMENT AFTER FINAL REJECTION

Mail Stop AF  
COMMISSIONER FOR PATENTS  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Further examination and consideration of this application are requested in view of the following Amendments and Remarks.

CLAIM AMENDMENTS

- 1-20 (Withdrawn from Consideration)
21. (Currently Amended) A multiple die electronic system comprising:  
a substrate having conductors formed thereon,  
a base IC die having a first surface facing the substrate and a second surface parallel to the first surface,  
a first secondary IC die residing between the first surface of the base IC die and the substrate and linked to the first surface of the base IC die through first conductive signal paths, and  
conductive contacts extending between the first surface of the base IC die and the conductors on the substrate for conveying signals between the base IC die ~~an~~ and the conductors on the substrate.
22. (Original) The multiple die electronic system in accordance with claim 21 wherein solder forms the first conductive signal paths.
23. (Original) The multiple die electronic system in accordance with claim 21 wherein the substrate is a printed circuit board substrate.